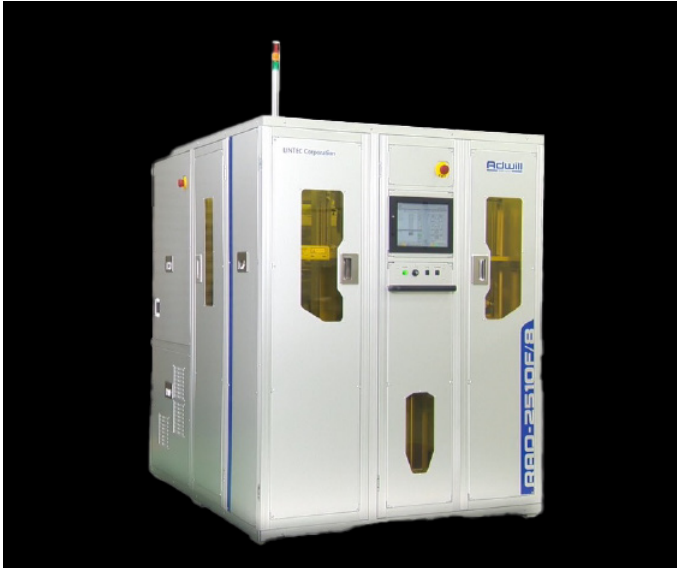


Wafer Mounter

# RAD-2510F/8



## Facility

Power Supply	Voltage	: AC200-230V±10% (AC190-253V)
	Frequency	: 50/60Hz
	Phase	: Single phase
Air Supply	Power consumption	: 1.5kW
	Air pressure	: 0.6-0.8MPa
	Air consumption	: <300L/min (ANR)
Vacuum Supply	Vacuum pressure	: <-80kPa

**Applicable Wafer Size** 100mm、125mm、150mm、200mm

**Size**  
Width(W) : 1,360mm  
Depth(D) : 1,830mm  
Height(H) : 1,800mm  
(excluding the signal tower and protruding parts)

**Weight** 1,500kg

**UPH** 120wafers/hour

The above processing capacity is based on following conditions:

Wafer : 200mm non-polished mirror wafer  
Dicing tape : G-11D from LINTEC

## Outline

- Fully-Automatic wafer mounter that is compatible with thin/warped wafers.
- Realization of high throughput by the optimization of transfer units.
- Reduction of tape consumption from the decrease in in-line pre-cutting tape pitch.

### Options

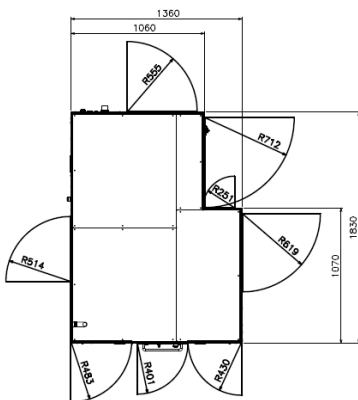
- Double Loader and Double Unloader Specification
- Dicing Tape In-Line Pre-Cutting
- Attachment Table Heater Specification
- Vision System (Wafer ID Reader & Barcode Attachment System)
- Host Communication Function (Communication Format: Conforms to SECS-I and HSMS/Software: Conforms to GEM)
- ESD Compatibility

### Suitable Tape

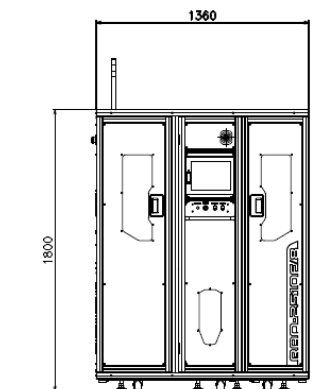
- Dicing Tape: Adwill D Series, G Series
- Dicing Die Bonding Tape: Adwill LE Tape
- Backside Coating tape: Adwill LC Tape

## External View

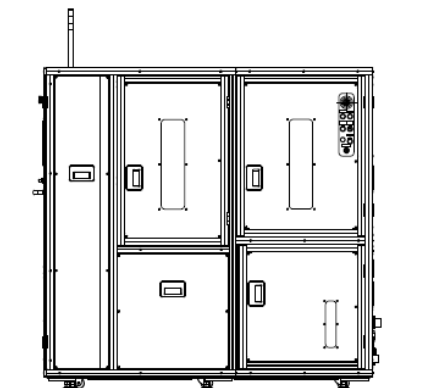
Unit:mm



Top View



Front View



Right Side View



**LINTEC Corporation** *Linking your dreams*

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<https://www.adwill-global.com/en>